

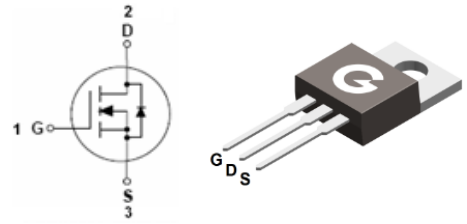
Features

- Reliable and rugged
- 100% avalanche tested

HF

Mechanical Data

- Case: TO-220AB
- Molding Compound: UL Flammability Classification Rating 94V-0
- Terminals: Matte tin-plated leads; solderability-per MIL-STD-202, Method 208



TO-220AB

Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
BL270N20H	TO-220AB	50 pcs / Tube	270N20H

Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	200	V
Gate-to-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (T _C = 25°C)	I _D	62	A
Continuous Drain Current (T _C = 100°C)		44	A
Pulsed Drain Current *1 (tp=10us)	I _{DM}	360	A
Single Pulse Avalanche Energy *3	E _{AS}	784	mJ

Thermal Characteristics

Parameter	Symbol	Value	Unit
Power Dissipation (T _C = 25°C)	P _D	375	W
Power Dissipation (T _C = 100°C)		187.5	W
Thermal Resistance Junction-to-Case	R _{θJC}	0.4	°C/W
Thermal Resistance Junction-to-Air *2	R _{θJA}	62.5	°C/W
Operating Junction Temperature Range	T _J	-55 ~ +175	°C
Storage Temperature Range	T _{STG}	-55 ~ +175	°C

Electrical Characteristics (@ $T_C = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
V_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	200	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 200V, V_{GS} = 0V (T_C=25^\circ\text{C})$	-	-	1	μA
		$V_{DS} = 200V, V_{GS} = 0V (T_C=55^\circ\text{C})$	-	-	5	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	± 100	nA
On Characteristics						
$R_{DS(ON)}$	Static Drain-Source On-resistance *4	$V_{GS} = 10V, I_D = 45A$	-	22	27	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	V
Dynamic Characteristics						
R_G	Gate Resistance	$V_{GS} = 0V, f = 1\text{MHz}$	-	3.4	-	Ω
C_{ISS}	Input Capacitance	$V_{GS} = 0V$	-	5871	-	pF
C_{OSS}	Output Capacitance	$V_{DS} = 25V$	-	392	-	
C_{RSS}	Reverse Transfer Capacitance	$f = 1\text{MHz}$	-	165	-	
Q_G	Total Gate-Charge	$V_{DD} = 160V$	-	130.4	-	nC
Q_{GS}	Gate to Source Charge	$V_{GS} = 10V$	-	22.1	-	
Q_{GD}	Gate to Drain (Miller) Charge	$I_D = 45A$	-	38.2	-	
Switching Characteristics						
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD} = 100V$	-	29	-	ns
t_r	Turn-on Rise Time	$V_{GS} = 10V$	-	45	-	
$t_{d(OFF)}$	Turn-Off Delay Time	$R_G = 4\Omega$	-	22	-	
t_f	Turn-Off Fall Time	$I_D = 45A$	-	41	-	
Source-Drain Diode Characteristics						
V_{SD}	Diode Forward Voltage *4	$I_{SD} = 45A, V_{GS} = 0V$	-	-	1.1	V
t_{rr}	Reverse Recovery Time	$I_F = 45A$	-	80	-	ns
Q_{rr}	Reverse Recovery Charge	$di/dt = 100A/\mu s$	-	160	-	nC

Notes:

1. Repetitive rating; pulse width limited by max. junction temperature
2. Surface mounted on FR-4 board
3. The E_{AS} data shows Max. rating. The test condition is $R_G = 25\Omega, V_{GS} = 10V, L = 0.5\text{mH}$
4. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$

Ratings and Characteristics Curves (@ $T_A = 25^\circ\text{C}$ unless otherwise specified)

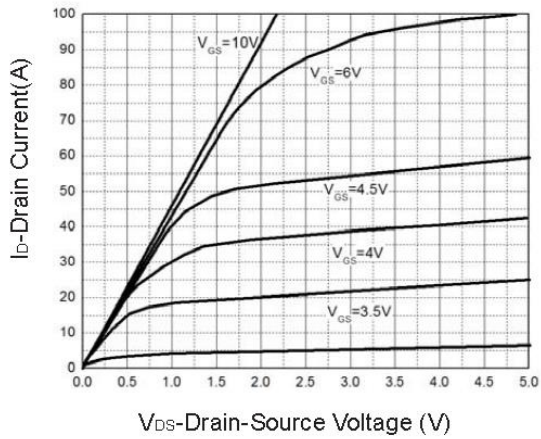


Fig 1 Typical Output Characteristics

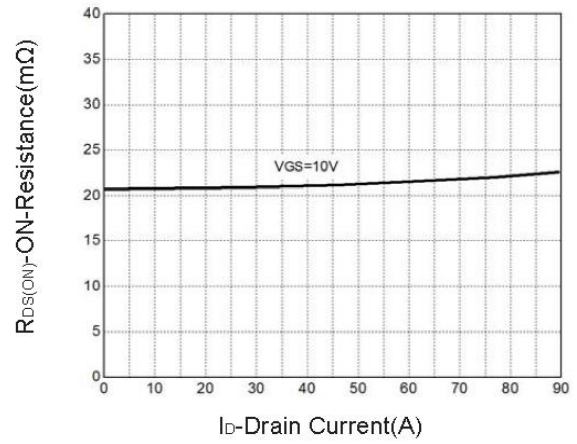


Fig 2 On-Resistance vs. Drain Current and Gate Voltage

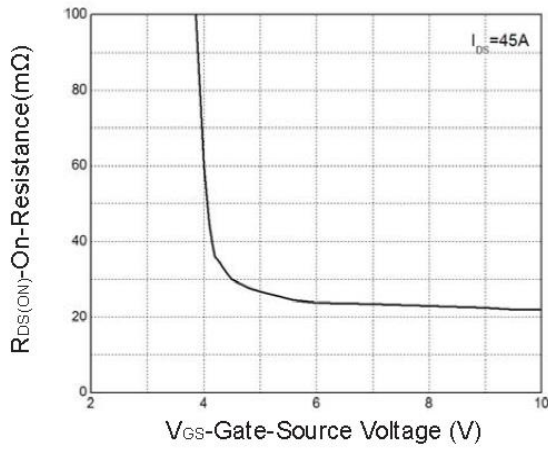


Fig 3 On-Resistance vs. Gate-Source Voltage

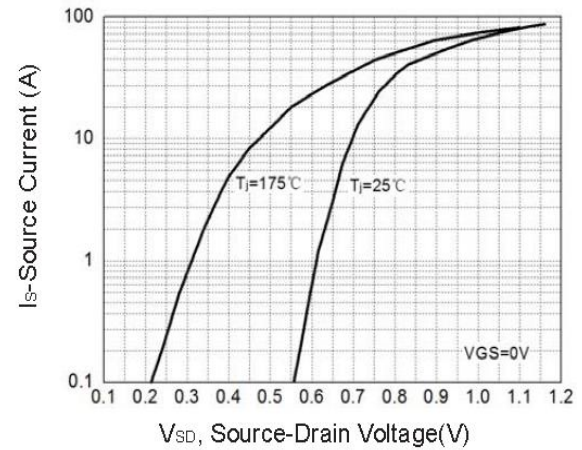


Fig 4 Body-Diode Characteristics

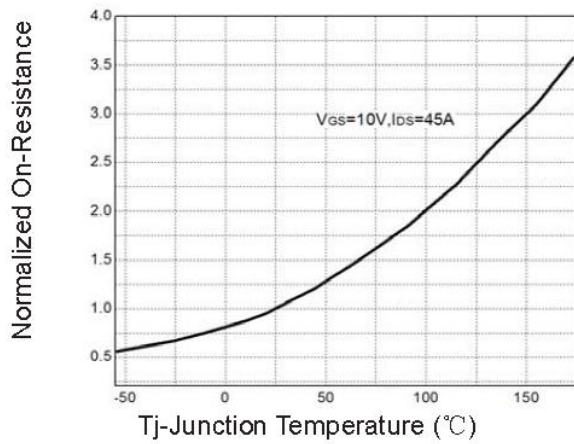


Fig 5 On-Resistance vs. Junction Temperature

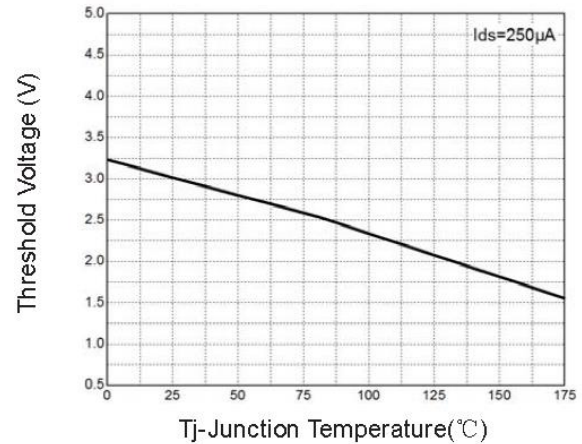


Fig 6 $V_{GS(th)}$ vs. Junction Temperature

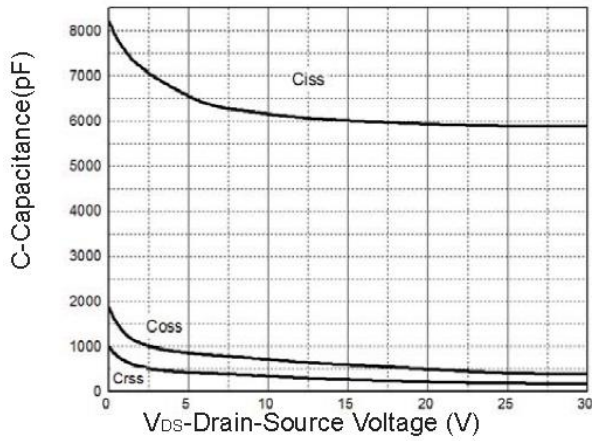


Fig 7 Capacitance Characteristics

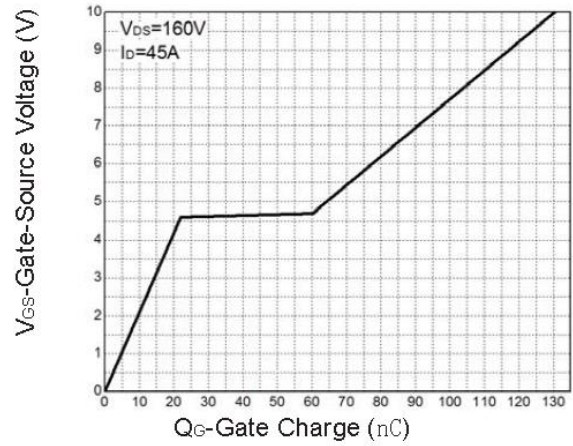


Fig 8 Gate-Charge Characteristics

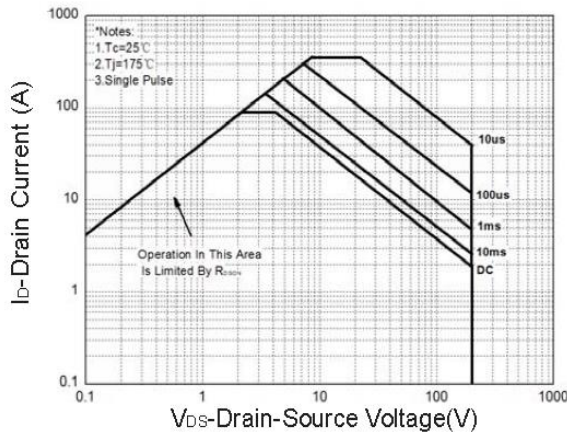


Fig 9 Safe Operation Area

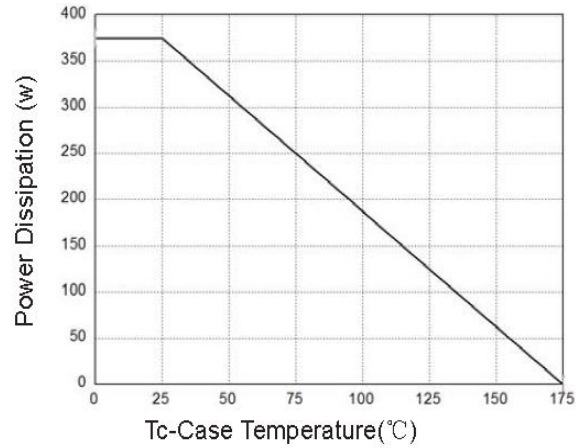


Fig 10 Power Dissipation

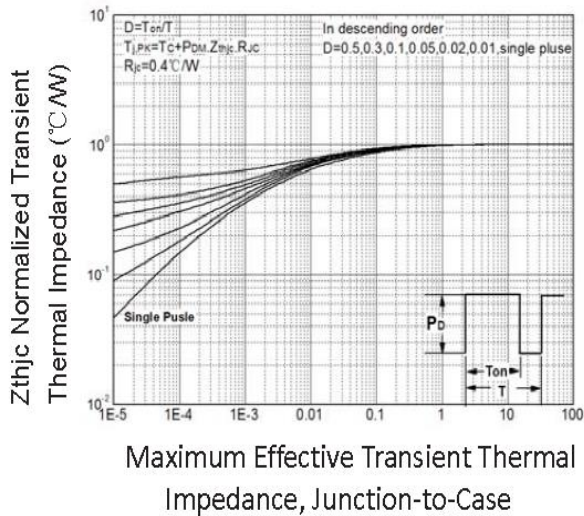


Fig 11 Thermal Transient Impedance

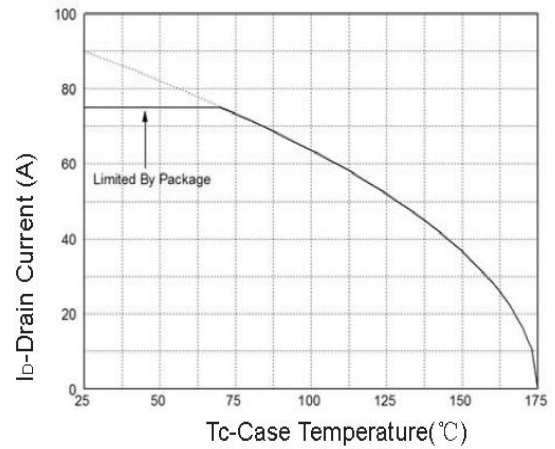
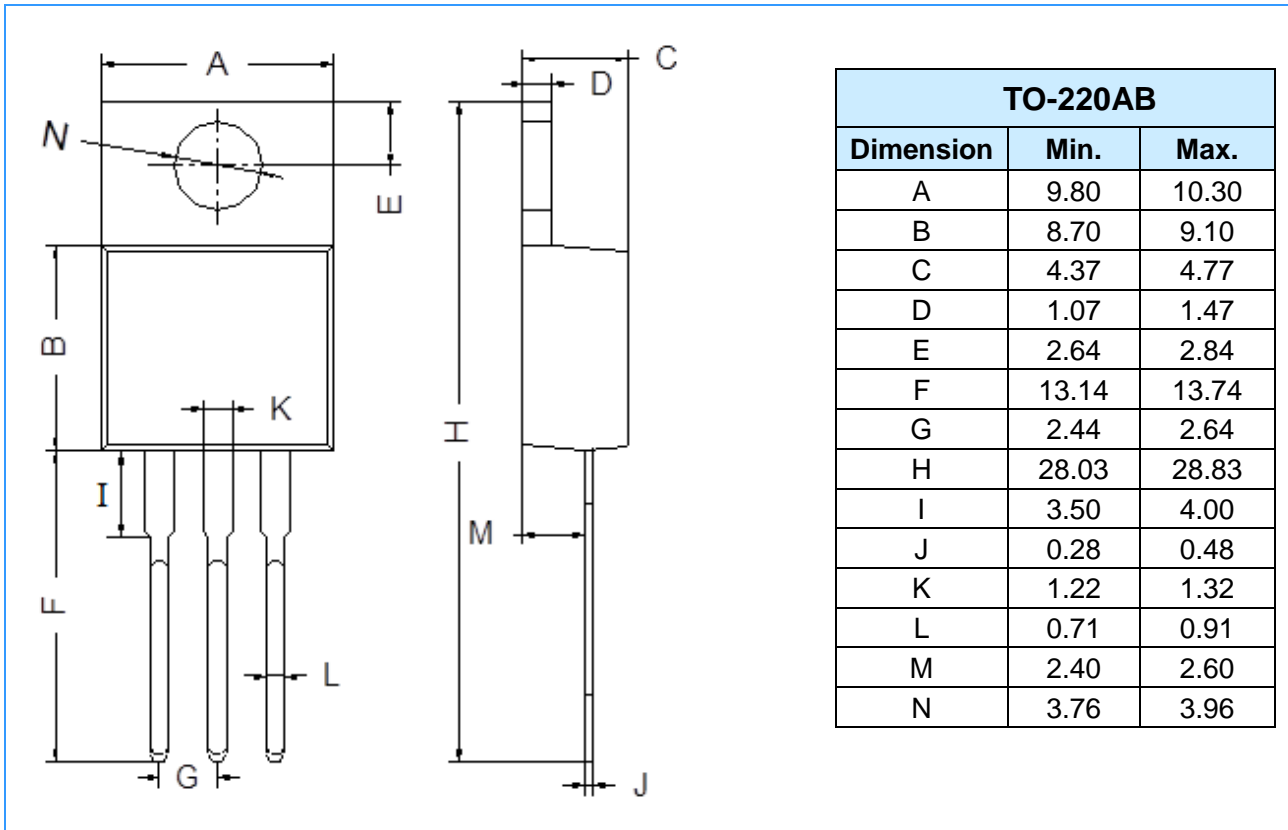


Figure 12 Maximum Continuous Drain Current vs. Case Temperature

Package Outline Dimensions (Unit: mm)



IMPORTANT NOTICE

Changzhou Galaxy Century Microelectronics (GME) reserves the right to make changes without further notice to any product information (copyrighted) herein to make corrections, modifications, improvements, or other changes. GME does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others.